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J. Carter

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): TANAKA, et al
Serial No.: 09/904,839
Filed: July 16, 2001
For: LEAD FRAME AND SEMICONDUCTOR DEVICE USING THE
LEAD FRAME AND METHOD OF MANUFACTURING THE
SAME
Group: 2814
Examiner: D. Farahani

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AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

March 6, 2003

Sir:

The following amendments and remarks are respectfully submitted in connection with the above-identified application in response to the Office Action dated October 7, 2002.

IN THE SPECIFICATION:

Page 1, please amend the paragraph beginning at line 4 as follows:

CROSS REFERENCE TO RELATED APPLICATION

This is a continuation of U.S. application Serial No. 08/820,228, filed March 18, 1997, now U.S. Patent No. 6,265,762, the subject matter of which is incorporated by reference herein.

Page 15, please amend the paragraph beginning at line 5 as follows:

The bonding for connecting the pad electrodes 11 to the points of the inner leads 4 is effected by the wires 13, but the pad pitch is made wider in the